

- [08] 2018/02/27@San Diego in USA
6th World Congress on Adhesion and Related Phenomena (WCARP-VI)
Adhesion property of heat-assisted plasma-treated polytetrafluoroethylene (PTFE)
○Y. Ohkubo, M. Shibahara, A. Nagatani, K. Honda, K. Endo, K. Yamamura

- [07] 2017/09/21@Shanghai in China
The 13th China-Japan International Conference on Ultra-Precision Machining Process (CJUMP2017)
The relationship between anodic oxidation rate and electric potential in electrochemical mechanical polishing of 4H-SiC (0001)
○X. Yang, Y. Ohkubo, K. Endo, K. Yamamura

- [06] 2017/09/21@Shanghai in China
The 13th China-Japan International Conference on Ultra-Precision Machining Process (CJUMP2017)
Polishing characteristics of reaction-sintered silicon carbide by plasma-assisted polishing
○R. Sun, K. Tsujiuchi, Y. Ohkubo, K. Endo, K. Yamamura

- [05] 2017/08/29@Tokyo in Japan
International Symposium on Novel Energy Nanomaterials, Catalysts and Surfaces for Future Earth
Nanoscale chemical imaging of oxygen storage and release particles by hard X-ray spectro-ptychography
○M. Hirose, N. Ishiguro, K. Shimomura, N. Burdet, H. Matsui, M. Tada, Y. Takahashi

- [04] 2017/08/27@Osaka in Japan
13th International Conference on Advanced Materials and Nanotechnology
Effect of O₂ or H₂ gas addition to Ar gas on surface modification of fluoropolymer using atmospheric pressure plasma –Application for highly adhesive Ag wiring pattern on plasma-treated fluoropolymer
○Y. Kodama, Y. Ohkubo, T. Oshita, T. Aoki, T. Nakagawa, K. Endo, K. Yamamura

- [03] 2017/08/18@Rochester in USA
SPIE Optifab
Measurement of a concave spherical mirror with sub-50 pm repeatability by 3D nanop profiler using normal vector tracing
○T. Kitayama, H. Shiraji, R. Kizaki, K. Yamamura, K. Endo

- [02] 2017/05/31@Hanover in Germany
17th International Conference of the European Society for Precision Engineering and Nanotechnology
Removal of subsurface damage of 4H-SiC wafer by plasma assisted polishing
○K. Tsujiuchi, C. Kageyama, K. Endo, K. Yamamura

● [01] 2017/05/31@Hanover in Germany

17th International Conference of the European Society for Precision Engineering and Nanotechnology

High rate abrasive-free polishing of single crystal diamond wafer by plasma assisted polishing

○K. Emori, K. Endo, H. Yamada, A. Chayahara, Y. Mokuno, K. Yamamura